

ABSTRACT OF THE DISCLOSURE

A polishing pad or other shaped article for the electrochemical mechanical polishing (ECMP) of a workpiece. The article includes an electrically-conductive compound which is
5 formed into a layer. The compound is formulated as an admixture which includes a polymeric component forming a continuous phase in the layer, and an electrically-conductive filler component forming a discrete phase within the continuous phase. With the workpiece and the layer being electrically connected and with an electrical bias being applied between the workpiece and the layer, the bias being capable of activating an
10 electrochemical reaction, the compound exhibits an overpotential for the activation of the reaction greater than the bias.